



## MS-30P PARQUET ADHESIVE

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**Product:**

MS-30P is a solvent, and water-free universal parquet adhesive.  
Suitable for bonding many types of parquet floors onto suitable indoor substrates.

**Technical data:**

Base	MS Polymer
Curing system	Chemical curing
Consistency	Paste
Colour	Pale brown/ dark brown
Specific gravity (DIN 53479)	Approx. 1,6 g/cm <sup>3</sup>
Brookfield viscosity (mPa.s)	Approx. 72.000 (HBT A/10)
Open time at 21°C and 50% RH	Approx. 30 minutes
Adjustability time at 21°C and 50% RH	Approx. 30 minutes
Set to load bearing	min. 24 hrs
Sanding/finishing	min. 24 hrs
Shear strength (EN14293) wood/wood	> 1N/mm <sup>2</sup>
Temperature resistance	-40°C to +90°C (cured)
Durability against ageing	Good
Total solids content	100% (solvent free)
Application rate	Depending on the subfloor 800 – 1200 g/m <sup>2</sup> by use of the SOUDAL-notched trowel for parquet

\* This varies according to ambient conditions such as temperature, humidity, substrate etc.

**Characteristics:**

- Ready to use, no mixing required
- Single component
- EC-1 label: very low emissions
- Solvent free
- Contains no water
- Free of isocyanates
- Easy to apply
- Forms stable peaks once applied by a notched trowel or spreader comb
- Rapid cure and build up of final bond strength
- High final bond strength (according to EN14293)
- Remains permanently elastic
- Suitable for underfloor heating

Remark: The directives contained in this documentation are the result of our experiments and of our experience and have been submitted in good faith. Because of the diversity of the materials and substrates and the great number of possible applications which are out of our control, we cannot accept any responsibility for the results obtained. In every case it is recommended to carry out preliminary experiments.



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**Applications:**

MS-30P is a solvent, and water-free universal parquet adhesive based upon MS Polymers. Suitable for indoor bonding of all types of wooden floors such as solid, stab, pre-finished, and on-end parquet, wood-plank, wood-block and laminates.

Suitable for use on porous and non-porous substrates such as mosaic, anhydrite, concrete, screeds, wood, chipboard and OSB Board (large particle size chipboard), including floors with underfloor heating.

MS-30P is also extremely suitable for bonding moisture sensitive wood onto moderately porous surfaces.

**Description:**

MS-30P cures by means of a chemical reaction within the adhesive. Once fully cured (approx. 24 hrs. at 21°C and 50% RH) an elastic and non-shrinkable adhesive layer is formed, which is resistant to moisture and heat. The adhesive has excellent adhesion to most common substrates used in the construction industry.

MS-30P contains no water or solvents, minimising the risk of deforming the parquet to a minimum.

**Packaging:**

*Colour:* light brown, dark brown

*Packaging:* PE bucket 6kg, PE bucket 16kg, 3 alu-bags in a plastic bucket (3 x 6 kg = 18kg).

Separate packaging permits flexibility in use.

**Shelf-life:**

- PE bucket 16kg at least 6 months in unopened packaging in a cool and dry storage at temperatures between +5°C and +25°C
- PE bucket with alu-bag (6kg), 3 alu-bags in a plastic bucket (3 x 6 kg = 18kg) at least 9 months in unopened packaging in a cool and dry storage at temperatures between +5°C and +25°C

**Substrate:**

Before installation of the parquet, the substrate should be checked to ensure it is suitable. Check the moisture content throughout the entire thickness of the substrate with a carbide or electric hygrometer.

The moisture content must be as recommended by the flooring manufacturer (generally max. 2% for sand cement substrates and max. 0,5% for anhydrite, measured with a carbide hygrometer. For substrates with underfloor heating the values are resp. max. 1,5% and 0,3%)

MS-30P should be applied to an even, dry, clean and smooth substrate, which is free from irregularities and cracks. Rests of old adhesives may affect the adhesion and must be removed mechanically. Loose or damaged surfaces must be repaired before the application of the adhesive.

Powdery surface can be treated (after consulting our technical service) with **Soudal WBPR-21 Deep Primer**.

Very porous surfaces can be treated (after consulting our technical service) with **Soudal WBPR-11 Surface Primer**.

Subfloors with a higher moisture content than described above can be treated (after consulting our technical service) with **Soudal EPR-31P**.

Smooth surfaces like anhydrite should be roughened and disposed of the top layer. Sanded subfloor must be vacuum cleaned with an industrial vacuum cleaner.

When installing a parquet floor on top of marble, terrazzo or ceramic tiles they must be first cleaned with caustic soda or another suitable cleaner. Once cleaned, rinse the tiles thoroughly with plenty of clean water. Ensure the floor is completely dry before applying the MS-30P.

***A preliminary compatibility test is recommended on every surface.***

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**Parquet:**

The parquet flooring must be acclimatised for several days in the area where it is to be installed. Leave the parquet in its original packaging until installation to avoid any deformation.

Check before installation that the moisture content of the wood is as recommended by the supplier, (generally 9% +/- 2%). If the humidity of the wood is more than 11% installation is not recommended

Allow a gap of 1 to 1,5 cm around the perimeter of the laid parquet, including any columns or structures, which penetrate the floor.

**Applying the adhesive:**

MS-30P should be acclimatised to room temperature before installation.

Apply the adhesive to the surface by means of a suitable notched **Soudal** trowel. Do not apply more to the surface than can be covered with parquet within 30 minutes. Slide the parquet onto the adhesive layer and tap into place or tamp down with a rubber hammer.

A minimum of 80% contact coverage is required to ensure a perfect adhesion. Loading the parquet with weights will improve the final bond strength. Wait at least 24 h before sanding and finishing the parquet.

Uncured MS-30P may be removed from tools and parquet with Soudal Adhesive cleaner. Cured adhesive must be removed mechanically.

**Health- and safety recommendations:**

Apply the usual industrial hygiene precautions.

Wear protective gloves.

Consult the label for more information.

**Recommendations:**

- Never install flooring on subfloors, which are not protected against possible rising damp.
- Do not apply the adhesive at temperatures below 15°C or above 25°C
- Minimum temperature of the substrate should be at least 15°C.
- Do not apply the adhesive when the relative humidity is above 75%.
- Never install flooring on a substrate which contains too much moisture or on substrates with a higher humidity value than recommended by the wood supplier.
- Never install wood which is too dry (<7% humidity). This can expand at higher humidity or when the humidity rises and cause damage.
- Do not install flooring if the walls and ceilings in the area are not dry (e.g. after plastering or painting etc.)
- When bonding parquet without tongue and groove, the board has to be at least 10mm thick. When bonding to a wooden subfloor over underfloor heating board should not be wider as 13cm. Insure enough nails are used (every 3cm in width and every 15-20cm in length)
- Do not dilute the adhesive.

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